

Index

- 3-D memory stack, 258
 3-D packaging, 31, 251–60
 benefits, 257
 chip stacking, 18–19, 20, 251, 256–7
 design types, 254
 multichip stacking, 19–24, 254
 package stacking, 251
 through-silicon vias, 259–60
 wafer stacking, 254–8
 40% rule, stencil dots and lines, 177
 abbreviations, 380–4
 Ablefill UF8807 underfill adhesive, 232
 Abzol solvent, 149
 accelerated testing, 291, 329
 acetylene-terminated polyimides, 94
 ACF *see* anisotropic conductive film
 acoustic impedance, 300
 acoustic microscopy, 281, 300–1, 302,
 369–70
 acoustic reflection, 301
 acronyms and abbreviations, 380–4
 acrylates, 100–1, 131–2
 acrylics, 100–1
 acrylonitrile-butadiene copolymer, 114
 addition-cured silicones, 89–91
 additives *see* formulation, additives
 adhesion loss, 292–301
 acoustic microscopy, 302
 adhesive coverage, 295
 moisture absorption, 301
 stresses, 295–302
 surface contamination, 294–5
 voids, 300
 wettability inadequacy, 294–5
 adhesion mechanisms, 47–51
 adhesion promoters, 48–9
 direct-chemical bonding, 48–9
 hydrogen bonding, 49–50
 mechanical interlocking, 50
 metallurgical bonding, 48
 vitreous bonding, 50–1
 adhesion promoters, 48–9
 adhesive coverage, 295
 adhesive particle detachment, 320
 adhesive-attached components, 293
 AEW (amine-equivalent weight), 87–8
 AK 225 solvent, 150
 alignment of optical fibers, 275–6, 280, 281
 aliphatic amines, 84
 alkaline condensates, 315
 alloys: thermal conductivities, 56–7
 aluminium fillers, 104
 aluminium surfaces, 314
 aluminium/polyimide interconnect
 (MCM-D) on silicon substrate, 225
 amide-amine curing agents (Dicy), 84–5
 amine curing agents, 82, 84, 85
 amine light stabilizers (HALS), 116
 amine-equivalent weight (AEW), 87–8
 ammonia, 315, 317, 319
 anaerobic adhesives, 27
 anhydride curing agents, 84, 85–6
 anhydride-cured bisphenol A epoxy, 124
 Anisomol AC-2056: anisotropic conductive
 adhesive, 268
 anisotropic adhesives, 7–8, 53–5, 239, 267,
 268, 324, 326
 anisotropic conductive film (ACF)
 adhesives, 239, 324, 326
 antimony compounds, 115
 antioxidants, 116
 application-specific integrated-circuits
 (ASIC), 19
 applications, 2, 8–11, 217–88
 general applications, 218–42
 capillary-flow underfill adhesives,
 224–5, 236–7

- applications (*Continued*)
- conductive adhesives as solder
 - replacements, 240–2
 - die-attach adhesives, 224, 225, 226, 227
 - solder replacement adhesives, 240–2
 - substrate-attach adhesives, 224, 225, 226, 227
 - surface-mount technology, 218–24
 - underfill adhesives, 224–40
 - historical developments, 24–9
 - specific applications, 242–85
 - 3-D packaging, 251–60
 - automotive electronics, 247–8
 - chip-scale packages, 250–1
 - electromagnetic interference shielding/
 - grounding, 274–5, 276
 - flat panel displays, 260–7
 - LED lighting, 267–72
 - lid sealing, 282–4
 - lighting, 267–72
 - medical devices, 248–50
 - military electronics, 242–5
 - optoelectronics, 275–80
 - organic light emitting diodes, 272–4
 - power circuits/devices, 284–5
 - radiofrequency identification units, 280–2
 - smart cards, 280–2
 - space electronics, 246–7
 - system-in-package, 260, 261, 262
 - vertical-stack packaging, 251–60
 - aqueous cleaners, 147–52, 153–6, 162–3, 165
 - Arathane 7760 polyurethane adhesive, 130
 - ARclear pressure-sensitive adhesives, 266
 - area-array devices/packages, 14
 - argon, 40, 166, 320
 - aromatic amines, 84
 - Arrhenius equation, 41
 - AsahiKlin organic solvents, 150–1
 - ASIC (application-specific integrated-circuits), 19
 - aspect ratio: stencil dot design, 180
 - assemblies: rework, 211–12
 - atomic absorption spectroscopy, 374
 - atomic oxygen, 247
 - auger pumps, 192
 - autoclave sterilization, 250
 - automated selective dispensing, 183–95
 - auger pumps, 192
 - die-attachment adhesives, 185–6
 - equipment, 189–92
 - flow rate, 193
 - linear-piston pumps, 192
 - material factors, 194–5
 - needle selection, 188–9
 - satellite dots, 195
 - surface-mount adhesives, 186–92
 - time-pressure pumps, 192
 - underfill adhesives, 192–4
 - automotive electronics, 30, 247–8
 - Axiom automated dispensing systems, 190
 - azeotropes, 147, 148–51, 157, 159, 160–1
 - B-staging, 39
 - ball-grid-arrays (BGAs), 11, 14, 15, 212
 - bare die devices, 9
 - bathtub curve, 322–4, 325
 - Bayer Chemicals, 95
 - BCC (bumped chip carrier), 252
 - bending stress, 370
 - BGAs *see* ball-grid-arrays
 - Bioact EC organic solvents, 148–9
 - biocompatibility, 249
 - bismaleimides, 92
 - bleedout, 40–1
 - blood compatibility: medical devices, 249
 - bond line thickness, 308–9
 - bond pad redistribution, 255–6
 - bond strength, 108, 367–9
 - bond-joint resistance, 358
 - bonding processes, 143–216
 - cleaning, 144–72
 - component placement, 197–8, 199–200
 - curing, 198–209
 - device placement, 197–8, 199–200
 - dispensing methods, 173–97
 - material/process requirements, 145
 - requirements, 145
 - rework, 209–12
 - surface treatments, 172–3
 - boron-nitride filled epoxy adhesives, 104
 - brominated flame retardants, 115
 - Brookfield viscometers, 45, 351
 - bumped chip carrier (BCC), 252
 - C of C (certificate of compliance), 330
 - Cab-O-Sil filler, 109

- calorimetry, 205–9
capacitance, 20, 129, 356
capacitor attachments, 20
capillary flow, 43–7
capillary-flow underfill adhesives:
 applications, 224–5, 236–7
 dispense patterns, 193
 process steps, 231
 suppliers, 236–7
car electronics, 30, 247–8
carbon nanotubes (CNTs), 110, 111
carbon-filled polymers, 52
catalysts, 77, 86–7, 89
catalytic-curing agents, 86–7
cavity packages, 13, 283
centrifugal cleaning, 164–6
centrifuge testing, 369
Century C-718 automated dispensing system, 190
ceramic materials: thermal conductivities, 57
ceramic multichip module (MCM-C), 226
ceramic packages, 15, 16, 284
ceramic printed circuits, 153–6
ceramic substrates, 21
ceramic thick film (MCM-C), 22, 225, 226
certificate of compliance (C of C), 330
CFC (chlorofluorocarbon) solvents, 146
Champion automated dispensing systems, 191
chemical analysis, 371–5
 gas chromatography, 372
 infrared spectroscopy, 372
 ionic content tests, 374–5
 mass spectrometry, 372–3
 residual gas analysis, 372–3
 total-mass loss, 373–4
 water vapor regained, 374
 weight loss during cure, 371
chemical mechanisms: electrical stability, 311–12
chemical resistance, 358–9
chemical surface treatments, 172–3
chemical-type classification, 3–4
chemically-etched stencils, 176
chemistry, 77–101
 acrylates, 100–1
 acrylics, 100–1
 cyanate esters, 98, 99
 epoxy adhesives, 77–88
modified cyclo-olefin thermosets, 98–100
polyimides, 91–4
polymer adhesives, 76–101
polyurethanes, 94–8
silicones, 88–91
silver-glass adhesives, 101
chip devices, 210
chip stacking, 18–19, 20, 251, 256–7
chip-connection methods, 12
chip-on-board (COB), 9, 23, 24
chip-on-flex (COF), 24
chip-on-glass (COG), 267
chip-scale packages (CSP), 15–18, 250–1, 252–3
“chips first” packaging, 23
chloride ions, 315, 374–5
chlorofluorocarbon (CFC) solvents, 146
Cho-Seal S6305 gasket, 276
chromatography, 372
circuit boards *see* printed-circuit boards
classifications, 2–11
 applications, 8–11
 chemical type, 3–4
 curing method, 5–6
 form, 2–3
 formulation, 5
 function, 6–8
 intended use, 8–11
 physical form, 2–3
 polymer type, 3–4
 tests, 347–9
cleaning, 144–72
 cleanliness assurance/testing, 168–72
 media comparison, 160
 methods, 159–68
 centrifugal cleaning, 164–6
 CO₂ jet cleaning, 168
 comparison of wet, dry, and solid media, 160
 dry cleaning, 166–8
 immersion cleaning, 164
 microphase cleaning, 147–52
 plasma cleaning, 166–8
 solid carbon dioxide cleaning, 168
 spray cleaning, 161–4
 thermal-phase cleaning, 147–52
 ultrasonic cleaning, 164
 vapor degreasing, 159–61
 solvent selection, 146–59

- cleaning (*Continued*)
testing, 168–72
wiring harnesses, 153–6
- CNTs (carbon nanotubes), 110, 111
- co-solvents, 147, 159
- CO₂ jet cleaning, 168
- COB (chip-on-board), 9, 23, 24
- coefficient of thermal expansion (CTE), 44, 61–2, 63–6
- adhesives, 64–5, 221, 222–3, 228–30, 234–5
- die-attach adhesives, 228–30
- epoxy adhesives, 123
- epoxy resins, 108
- fillers, 107, 108
- glass transition temperatures, 64–5
- mismatches, 298–300
- non-organic materials, 63
- plastics, 64–5
- substrate materials, 273
- substrate-attach adhesives, 228–30
- surface-mount adhesives, 221, 222–3
- test methods, 367
- thermomechanical analysis curve, 66
- underfill adhesives, 234–5
- COF (chip-on-flex), 24
- COG (chip-on-glass), 267
- collected volatile condensable materials (CVCM) test, 246
- colored pigments, 117
- “compensating films”, 262–4
- component-attach materials: thermal properties, 272
- components:
failure rate modeling, 327–8
placement systems, 197–8, 199–200
rework, 210, 211
stresses, 327
- condensation-cured silicones, 89, 90
- conductive epoxy bumps, 256
- conductive particles, 7
- conductivity, 51–4, 102–7, 133
- constant acceleration, 369
- contact angles:
corona discharge, 172
fillet shape factors, 47
oil films, 40
plasma cleaning effect, 168, 171
residue detection, 168–71
test methods, 353
- underfill adhesives, 44, 47
wettability, 38, 39
- contact cards, 280
- contact loss, 310–12
- contact resistance, 309–10
- contact type dispensing *see* automated selective dispensing
- contamination:
bleedout, 40
identification, 145
oxide removal, 167
surfaces, 294–5
types, 145. *See also* corrosion
- conversion factors, 379–80
- copper, 102, 104, 241
- corona discharge, 172
- corrosion, 314–16
curing agents, 314–15
ionic impurities, 315–16
test methods, 359. *See also* contamination
- COS (chip-on substrate) *see* chip-on-board
- coupling agents, 48–9, 113
- coverage of adhesive, 295
- overlays, 24
- cracks:
dye penetrant test, 291
fracture mechanics, 303–7
loading modes, 306
- cross-linkers: silicones, 89
- CSP *see* chip-scale packages
- CTE *see* coefficient of thermal expansion
- curing:
agents
aliphatic amines, 84
anhydrides, 84
aromatic amines, 84
corrosion, 314–15
definition, 77
epoxy adhesives, 83–4
epoxy resins, 80–2, 84
levels, 87–8
Lewis acids/bases, 84
polyamides, 84
bonding processes, 198–209
comparison of methods, 201
degree of cure, 204–9
differential scanning calorimetry, 205–9
Fourier Transform Infra-Red spectroscopy, 204–5, 206, 207

- method comparison, 201
microwave curing, 203
moisture curing, 203–4
overcuring, 204
schedules, 204–9
spectroscopy, 204–5, 206, 207
thermal curing, 201–2
UV curing, 202–3
variable-frequency microwave curing, 6, 203
visible light curing, 202–3
- conditions
flexural strength, 70
glass transition temperature, 68–70
modulus, 70
stress effect, 71
- contact resistance, 309–10
- formulations, 5
- methods, 5–6
- polyimides, 92
- resistance change, 309–10, 311
- schedules, 5, 37, 204–9
- die-attach adhesives, 228–30
solder replacement adhesives, 243–4
substrate-attach adhesives, 228–30
surface-mount adhesives, 222–3
underfill adhesives, 234–5
- temperature, 68, 221
- time-temperature-transformation diagram, 68
- torque strength, 37
- UV-curing adhesives, 277–9
- volume resistivity, 53
weight loss during cure, 371
- current density, 309–10
- current-carrying capacity, 357–8
- curvature radius, 296, 370–1
- CVCM (collected volatile condensable materials) test, 246
- cyanate esters, 98, 99, 129–31
- cyanoacrylates, 27, 101, 276
- degradation, 116
- delamination, 292–301
acoustic microscopy, 302
adhesive coverage, 295
moisture absorption, 301
stresses, 295–302
surface contamination, 294–5
- voids, 300
wettability inadequacy, 294–5
- density:
solvents, 158, 159
test methods, 352–3
- deposited thin film (MCM-D), 22, 225
- DETA (diethylenetriamine), 205, 207
- device placement, 197–8, 199–200
- DF *see* dissipation factor
- DGEBA *see* diglycidylether of bisphenol A
- diagnostic electronics, 249
- diamines, 93
- diamond fillers, 104
- dianhydrides, 93
- Dicy (amide-amine curing agents), 84–5
- die bonding, 12
- die fracture, 302–3
- die interconnection, 258
- die mounting, 354–5
- die removal, 210–11
- die-attach adhesives:
applications, 224, 225, 226, 227
automated selective dispensing, 185–6
coefficient of thermal expansion, 228–30
cure schedule, 228–30
defects, 354
fractures, 302
intended use, 8–9
ionic impurities, 228–30
outgassing, 247
pot life, 228–30
properties, 228–30
shelf life, 228–30
specifications, 331, 332–3
strength testing, 369
suppliers, 228–30
testing, 332–3
thermal conductivity, 228–30
viscosity, 228–30
- voids, 300
volume resistivity, 228–30
- die-shear tests, 368
- dielectric constant, 128, 356–7
- dielectric films, 24
- DieMat DM6030 adhesives, 273
- diethylenetriamine (DETA), 205, 207
- differential scanning calorimetry (DSC), 205–9, 361–2
- digital lighting, 269, 270

- diglycidylether of bisphenol A (DGEBA), 78, 80–2, 107, 206, 207, 208
diluents, 113
dimension units/equivalents, 379
DIPs (dual-in-line packages), 13
direct-chemical bonding, 48–9
DIS-A-PASTE polyurethane adhesives, 130
DispenseJet DJ-2100 valve, 196
dispensing methods, 173–97
 advantages/disadvantages, 175
 automated selective dispensing, 183–95
 comparison, 175
 cross-reference, 176
 jet dispensing, 195–7
 pin transfer, 182, 183
 preforms, 197
 screen printing, 173, 174–81
 stamp transfer, 182–3
 stencil printing, 173, 174–81
 tape attachment, 197
 yield value, 180
display cell assembly, 262–5, 266
dissipation factor (DF) tests, 356–7. *See also* stress dissipation, thermal dissipation
DM6030 adhesives: LED attachment, 273
dots and lines: stencil design, 177, 179
Dow Corning, 27
dry cleaning, 166–8
dry nitrogen, 317, 318–19
dry-heat sterilization, 250
DSC *see* differential scanning calorimetry
dual-in-line packages (DIPs), 13
DuPont, 25, 27
durometer test, 292
dye penetrant test, 291
- ECAs (electrically conductive adhesives), 309–10
Eccobond stencil printing adhesive, 181
EEW (epoxy-equivalent weights), 80, 81
elastic modulus *see* modulus of elasticity
electrical conductivity, 51–4, 102–7, 133
electrical connections, 6–8, 51–4, 55
electrical contact loss, 310–12
electrical ignition tests, 366
electrical properties, 124–5, 126
electrical resistance, 51
electrical stability, 309–14
aluminium surfaces, 314
chemical mechanisms, 311–12
contact loss, 310–12
contact resistance, 309–10
epoxy stability on aluminium surfaces, 314
semiconductor devices, 310–12
solder replacement, 312–14
test methods, 357
electrical tests, 355–8
 current-carrying capacity, 357–8
 dielectric constant, 356–7
 dissipation factor, 356–7
 electrical stability, 357
 interconnect resistance, 357–8
 metal migration, 358
 volume resistivity, 356
electrically conductive adhesives (ECAs), 36, 240–2, 309–10
electrically conductive paste, 132
electrically insulative adhesives, 8, 270–1
electroformed stencils, 176
electromagnetic interference (EMI)
 shielding/grounding, 274–5, 276
electronic component specifications, 245
EMI *see* electromagnetic interference
emission spectrographic methods, 374
emulsion cleaners, 147
encapsulants, 23
end sealants, 265
engine controller, 227
environmental tests, 358–60
 chemical resistance, 358–9
 corrosion, 359
 fungus resistance, 359–60
 hydrolytic stability, 360
 moisture absorption, 360
 radiation effects, 359
 solvent resistance, 358–9
EPAK Electronics Limited, 165
Epo-Tek adhesives, 9, 39, 181
epoxy adhesives, 5, 76
 amide-amine curing agents, 84–5
 amine curing agents, 82, 85
 anhydride curing agents, 85–6
 calorimetry, 208
 catalytic-curing agents, 86–7
 chemistry, 77–88
 curing agents, 83–4
 levels, 87–8

- differential scanning calorimetry, 208
epoxy resins, 78–82
lid sealing, 282–4
PEEK film comparison, 123, 124
percolation point, 52
polyamides, 82–4
polymerization with a Lewis base catalyst, 87
properties, 121–5
adhesion, 123
electrical properties, 124–5
purity, 122–3
tensile-shear strength, 108
thermal properties, 103, 123
thermomechanical properties, 123
purification improvements, 27
silver fillers, 7, 8, 105–6
thermogravimetric analysis, 123
thermomechanical analysis curve, 66
volume resistivity, 53, 54
epoxy bumps, 256
epoxy resins, 78–82
adhesive formulations, 81
chain propagation, 79
chlorine atom displacement by hydroxyl group, 79
coefficient of thermal expansion, 108
curing, 80–2
epoxy-equivalent weights, 80, 81
filler content, 108
generalized synthesis reaction, 79
historical developments, 24–7
hydroxyl group displacement reaction, 79
properties, 81
structures, 78
suppliers, 81
synthesis reaction, 79
termination step, 79–80
types, 81
viscosity, 81
Epoxy Technology Loctite, 181
epoxy-equivalent weights (EEW), 80, 81
epoxy-sealed packages, 284
equipment:
aqueous cleaners, 162–3
automated dispensing systems, 189–92
centrifugal cleaners, 165
component placement systems, 198, 199–200
HaakeRheo equipment, 45
in-line modular surface-mount technology, 220
plasma cleaners, 167–8, 169–70
screen/stencil printing, 180
semi-aqueous cleaners, 162–3
ultrasonic cleaners, 161
vapor degreasers, 161
EtO (gaseous ethylene oxide) sterilization, 250
expansion coefficients *see coefficient of thermal expansion*
failure methodology, 290–3
failure modes/mechanisms, 292–321
adhesion loss, 292–301
adhesive fractures, 303–7
adhesive particle detachment, 320
adhesive quality, 320–1
corrosion, 314–16
delamination, 292–301
detachment of adhesive particles, 320
die fracture, 302–3
electrical stability, 309–14
fracture mechanics, 303–7
loss of adhesion, 292–301
outgassing and moisture, 316–20
particle detachment, 320
quality of adhesives, 320–1
thermal impedance, 307–9
Weibull analysis, 323–4
failure rate modeling, 327–8
fast-cured adhesives, 201
fiber pigtailed modules, 280, 281
fillers, 51–4, 102–10
bond strength, 108
coefficient of thermal expansion, 107, 108
electrical conductivity, 102–7
flow properties, 108–9
particles, 42
percolation threshold, 58, 60
pot life extension, 110
shrinkage reduction, 107–8
thermal conductivity, 58–60, 61, 102–7
thermal stability, 107
fillets, underfill, 46–7
film adhesives, 3, 4, 9, 118–20
applications, 238
chip stacking, 256–7

- film adhesives (*Continued*)
 properties, 132–3, 134–6
 semiconductor die attachment, 134
 substrate attachment, 135–6
 suppliers, 238
- “fingerprint region”, spectroscopy, 321, 322
- flame photometry, 374
- flame retardants, 114–16
- flammability:
 flame retardants, 114–16
 tests, 365, 366
- flat panel displays (FPDs), 260–7
 display cell assembly, 262–5, 266
 front/rear panel processing, 260–2, 263
 module assembly, 265–7, 268
- flex interposer-based CSPs, 17–18, 253
- flexibilizers, 113–14
- flexible circuits, 23–4
- Flexobond 442 polyurethane adhesive, 130
- flexural modulus, 70, 297, 366–7
- flexural strength, 70
- flip-chip devices, 10–11, 12, 14
 reliability, 296
 underfilling, 224–40
 Weibull analysis, 324, 326
- flow properties *see* rheology
- fluorocarbons, 320
- flux residue removal, 158, 159
- FLX2011 component placement system, 200
- force: conversion factors, 379
- formulation:
 additives, 101–17
 colored pigments, 117
 coupling agents, 113
 diluents, 113
 fillers, 102–10
 flame retardants, 114–16
 flexibilizers, 113–14
 indicators, 117
 nanofillers, 110–12
 pigments, 117
 stabilizers, 116
 thixotropic agents, 112–13
- classification, 5
- processes, 117–21
 film adhesives, 118–20
 frozen adhesives, 121
 paste adhesives, 117–18, 119
 preform adhesives, 118–20
- premixed frozen adhesives, 121
- Fourier Transform Infra-Red (FTIR)
 spectroscopy, 204–7, 292, 320–2
- FPDs *see* flat panel displays
- fracture mechanics, 303–7
- fracture toughness, 305
- front panel processing, 260–3
- frozen adhesives, 3, 121
- FTIR *see* Fourier Transform Infra-Red
- functions of adhesives, 6–8, 35–74
- fungus resistance tests, 359–60
- gallium arsenide (GaAs) devices, 54–5
- galvanic corrosion, 312
- gamma radiation sterilization, 250
- gas chromatography, 372
- gaseous ethylene oxide (EtO) sterilization, 250
- gaskets: electromagnetic shielding, 276
- gel time, 39–40
- gelation, 71
- General Electric, 25, 27
- glass die bonding, 50–1
- glass transition temperature, 62–6, 68–70, 367
- glob tops, 23
- gold fillers, 102, 104
- goniometers, 353
- government documents: test standards, 350
- green strength measurement, 219–20, 221
- “green” technology, 31
- grounding: electromagnetic interference, 274–5
- guarded-hot-plate method, 362–3
- guidelines, 336, 340–1
- “gull wing” leads, 13, 14
- H-bonding (hydrogen bonding), 49–50
- Haake rotoviscometer, 351
- halide-containing adhesives, 115
- HALS (hindered amine light stabilizers), 116
- hardeners: definition, 77
- hardness tests, 292, 366
- hazardous materials restrictions, 336–42
- HCFCs (hydrochlorofluorocarbons), 146, 147
- HDI overlay packaging process, 22–3
- health and safety, 112, 114

- hearing aids, 248
heat dissipation, 54–60
heat-cured adhesives, 5, 201–2
heat-flow-meter method, 363–4
heritage data, 329
HFE-71 azeotropes, 151, 159
HFE-7100 co-solvent, 159
high-density interconnect (HDI) overlay process, 22–3
high-density modules, 210–11
high-modulus adhesives, 298, 299
hindered amine light stabilizers (HALS), 116
historical developments, 24–9
hot-melt adhesives *see* thermoplastic adhesives
humidity resistance, 126
humidity/temperature exposure, 129
hybrid microcircuits, 20–1, 226
hydrocarbon films, 40
hydrochlorofluorocarbons (HCFCs), 146, 147
hydrofluoroether cleaning solvents, 157
hydrogen bonding, 49–50
hydrolytic stability, 360
“I” dispense pattern, 193, 194
IC (integrated circuits), 354
ignition tests, 366
imaging sensors, 260
imidization: polyimides, 92
immersion cleaning, 164
impedance, 300, 307–9
in-line modular surface-mount technology, 220
in-process controls, 330
index of refraction, 277–9, 355
indicators, 117
industry documents: test standards, 350
infant-mortality period: bathtub curve, 323, 324
infrared spectroscopy (IR), 206, 207, 208, 372
innovative technologies, 31
inorganic materials:
 coefficient of thermal expansion, 63
 thermal conductivities, 57
inspections, 329–30. *See also* testing
integrated circuits (IC), 354
interconnect resistance, 357–8
interconnect substrates, 20, 22
intermediate-modulus adhesives, 298, 299
ionic content tests, 374–5
ionic impurities:
 corrosion, 315–16
 die-attach adhesives, 228–30
 solder replacement adhesives, 243–4
 substrate-attach adhesives, 228–30
 underfill adhesives, 234–5
IPC-CA-821 requirements, 331, 337–9
IR *see* infrared spectroscopy
isotropic adhesives, 7
isotropic conduction, 52–3, 54
JEDEC J-STD-030 guideline, 336, 340–1
jet cleaning, 168
jet dispensing, 195–7
junction temperature, 269, 272
Kauri-Butanol (KB) value, 148–51, 157–8
“L” dispense pattern, 193, 194
lamine multichip modules (MCM-L), 227
lamine-substrate-based CSP, 253
laser-cut stencils, 176
laser-flash method, 364
laser-to-fiber passive alignment, 281
LCDs (liquid-crystal displays), 260–7
lead-on-chip (LOC), 18
lead-soldering, 11, 26, 29
leadframe-based CSPs, 17, 252
leadframes, 17, 18, 41, 252, 294–5
LED attachment, 273
LED lighting, 31, 32, 267–72
Lenium, 148
Lewis acids, 84, 87
Lewis bases, 84, 86–7
Lewis and Nielsen model, 58, 60, 61
lid sealing, 282–4
lid-attach adhesives, 9
light intensity: degradation with time, 271
light-cured adhesives, 5–6
light-emitting diodes (LEDs), 31, 32, 267–73
linear polymers, 4
linear-piston pumps, 192
liquid adhesives, 2
liquid-crystal displays (LCDs), 260–7

- loading modes, 305–6
 LOC (lead-on-chip), 18
 Loctite:
 anaerobic adhesives, 27
 Chipbonder 3607, 37
 needle map, 189
 stencil printing adhesives, 181
 underfill adhesives, 232
 loss of adhesion *see* adhesion loss
 low-modulus adhesives, 298, 299
 low-stress adhesives, 8, 60, 61, 62
 lubricants, 103–7
 lumen maintenance projection, 271
 luminous transmittance, 355
- machine dispensing *see* automated selective dispensing
 magnesium oxide nanofillers, 111
 main sealants, 264
 manufacturers *see* suppliers
 market trends, 30–2
 mass spectrometry, 317, 372–3
 MCM (multichip modules), 21–2, 225, 226, 227
 MCM-C (ceramic thick film), 22, 225, 226
 MCM-D (deposited thin film), 22, 225
 MCM-L (plastic laminate), 22, 227
 MCOT (modified cyclo-olefin thermoset) adhesives, 27–8, 98–100, 131, 132
 mean time between failures (MTBF), 327
 mechanical attachment, 6, 36–51
 adhesion mechanisms, 47–51
 rheology, 41–7
 wettability, 37–41
 mechanical interlocking, 50
 mechanical tests, 365–71
 acoustic microscopy, 369–70
 bond strength, 367–9
 coefficient of thermal expansion, 367
 curvature radius, 370–1
 flexural modulus, 366–7
 glass-transition temperature, 367
 hardness, 366
 modulus and elongation, 366–7
 radius of curvature, 370–1
 tensile modulus, 367
 medical electronic devices, 248–50
 Megasolv NOC organic solvent, 148
- metal migration, 316, 358
 metal oxide removal, 167
 metal surfaces: solder replacement stability, 312–14
 metallurgical attachment, 25, 26, 29, 48
 metals: thermal conductivities, 56–7
 Method 5011, 30, 331, 334–5
 microcircuits, 11, 20–1, 29
 MicroMax automated dispensing systems, 191
 Micronox organic solvent, 151
 microphase cleaners, 147–52
 microscopy, 281, 291, 300–1, 302, 369–70
 microwave curing, 6, 203
 MIL-HDBK-217 handbook, 324–8
 MIL-STD-883 specification, 30, 331, 334–5
 military electronics, 242–5
 miniaturization, 30, 248
 modeling of reliability, 321–8
 modified cyclo-olefin thermoset (MCOT) resins, 27–8, 98–100, 131, 132
 module assembly, 265–7, 268
 modulus of elasticity (MOE), 297–8, 299
 solder replacement adhesives, 243–4
 substrate materials, 273
 surface-mount adhesives, 221
 test methods, 367
 modulus and elongation tests, 366–7. *See also* flexural modulus
 MOE *see* modulus of elasticity
 moisture:
 absorption, 234–5, 277–9, 301, 360
 curing, 6, 91, 95–8, 203–4
 outgassing, 316–20
 permeation, 284
 retention, 152
 tests, 360
 underfill adhesives, 234–5
 moisture-cured adhesives, 6, 91, 95–8
 moisture-cured polyurethanes, 95–8
 moisture-cured silicones, 91
 moisture-vapor transmission rates (MVTRs), 126
 motor vehicles, 30, 247–8
 MTBF (mean time between failures), 327
 multichip modules (MCM), 21–2, 225, 226, 227
 multichip packaging, 19–24, 254

- multilayer circuit boards, 10
multilayer thick-film digital filters, 225
multilayer thick-film hybrid microcircuits, 226
MVTRs (moisture-vapor transmission rates), 126
MY100 component placement systems, 199

nanofillers, 31, 110–12
nanotechnology, 110–12
NASA:
 outgassing tests, 246
 polymeric material tests, 246
 specifications, 27, 30, 331, 332–5
needle dispensing *see* automated selective dispensing
needle selection, 188–9
Newtonian flow, 42–3
NFU *see* no-flow underfills
nichrome resistors, 315
nickel fillers, 104
nickel nanoparticles, 112
Nielsen model, 58, 60, 61
nitrogen analysis, 317, 318–19
no-flow underfills (NFU), 226–38
 applications, 236–7
 dispense patterns, 233–8
 process steps, 233
 suppliers, 236–7
no-stress adhesives, 61, 62
noise detection, particle impact, 291, 320
non-cavity packages, 13
non-contact dispensing, 195–7
non-lead solders, 240
non-Newtonian flow, 42–3
non-noble metal surfaces: solder replacement stability, 312–14
non-organic materials *see* inorganic materials
nonconductive adhesives, 8
nondestructive tests, 330–1
nonpolar solvents, 146
Novec hydrofluoroether cleaning solvents, 157

OE (optoelectronics), 275–80
oil films, 40
OLEDs (organic light emitting diodes), 272–4
on-delay: automated dispensing, 185
one-part adhesives, 3
optical fiber alignment, 275–6, 280, 281
optical films, 262–4
Optimum Console cleaning systems, 162
optoelectronics (OE), 275–80
organic light emitting diodes (OLEDs), 272–4
organic solvents, 146–7, 148–51
organic-solderability preservative (OSP) copper, 241
organophosphorous compounds, 115–16
organosilanes, 48, 49, 113
OSP (organic-solderability preservative), 241
outgassing:
 die-attach adhesives, 247
 moisture, 316–20
 substrate-attach adhesives, 247
 tests, 246
 thermal curing, 202
 thermal impedance, 309
overcuring, 69, 204
oxidation, 116, 173
oxide contaminant removal, 167
oxide filled epoxy adhesives, 104
oxygen: atomic, 247
oxygen plasma cleaning, 40, 167

pacemakers, 249
package stacking, 251
packaging technologies, 12–24
 adhesive requirements, 245
 multichip packaging, 19–24
 single-chip packaging, 12–19
Part A / Part B two-part adhesives, 3
part stress analysis, 327
particle detachment, 320
particle getters, 11
particle impact noise detection (PIND) test, 291, 320
parts count reliability prediction, 328
paste adhesives, 2, 29, 117–18
 electrically conductive paste, 132
 formulations, 119
 thermally conductive paste, 132
 underfills, 239
PEEK film: epoxy adhesive comparison, 123, 124

- peel tests, 368
PEMs *see* plastic-encapsulated microcircuits
percolation threshold, 52, 58, 60
PFI (polymer-film interconnect), 240
PGAs (pin-grid arrays), 14–15, 16
Phillips Lumiled White LXM3-PWx1 LED light, 271
photometry, 374
physical form of adhesives, 2–3
physical tests, 346–55
 contact angle, 353
 density, 352–3
 luminous transmittance, 355
 refractive index, 355
 slump, 352
 specific gravity, 352–3
 spread, 352
 surface energy, 353
 surface tension, 353
 thixotropy, 351–2
 viscosity, 346–51
 visual inspection, 353–5
physics of failure (PoF), 290–2, 293
pigments, 117
pin transfer, 182, 183
pin-grid arrays (PGAs), 14–15, 16
PIND *see* particle impact noise detection
placement systems, 197–8, 199–200
plasma cleaning, 40, 166–8, 169–70
plasma treatment, 173
plastic laminate (MCM-L), 22, 227
plastic stencils, 176–7, 178
plastic-encapsulated leadless chip carrier (PLCC), 184
plastic-encapsulated microcircuits (PEMs), 29, 292, 293
plasticizers, 114
plastics, 59, 64–5
platinum fillers, 104
PLCC (plastic-encapsulated leadless chip carrier), 184
PoF (physics of failure), 290–2, 293
polar solvents, 146
polarizer attachment, 266
polarizer films, 262, 264–5
polyamides, 82–4
polyimides:
 acetylene-termination, 94
capacitance increase, 129
chemistry, 91–4
curing, 92
diamine reactants, 93
dianhydride reactants, 93
dielectric constant, 128
imidization, 92
precursors, 92
properties, 127–8
reactions, 92
relative humidity effect, 128
temperature/humidity exposure, 129
thermal weight loss, 127
polyisocyanates, 96–7
polymer adhesives, 2, 3–4
 advantages/limitations, 26
 chemistry, 76–101
 historical developments, 25
 metallurgical comparison, 26, 29
 thermal conductivities, 58
polymer collars, 240
polymer resins, 89
polymer structures, 4
polymer surfaces: plasma treatment, 173
polymer synthesis *see* chemistry
polymer-film interconnect (PFI), 240
polymeric materials, 334–5, 374–5
polyols, 96–7
polysiloxaneimides, 92
polyurethanes:
 chemistry, 94–8
 historical developments, 25, 27
 moisture-curing polyurethanes, 95–8
 polyisocyanate starting materials, 96–7
 polymerization reaction, 94
 polyol starting materials, 96–7
 properties, 128–9, 130
 suppliers, 130
 toxicity, 114
 viscosity, 130
popcorn effect, 27–8, 29, 301
pot life, 39–40
 die-attach adhesives, 228–30
 fillers, 110
 solder replacement adhesives, 243–4
 substrate-attach adhesives, 228–30
 surface-mount adhesives, 222–3
 viscosity, 194
power circuits/devices, 284–5

- pre-applied underfills, 240
precursors: polyimides, 92
prediction of reliability, 321–8
preform adhesives *see* film adhesives
premixed frozen adhesives, 121
pressure: conversion factors, 379
pressure-sensitive adhesives, 266
primers, 172
printed-circuit boards:
 automated dispensing, 184
 cleaning, 147, 153–6
 surface-mount technology, 10,
 218–19
printed-wiring assembly (PWA), 10
printed-wiring boards (PWBs), 221
processes *see* bonding processes
product acceptance, 330–1
promoters, 48–9
properties, 121–36
 acrylates, 131–2
 adhesive comparison, 122
 anisotropic adhesives, 268, 326
 aqueous cleaners, 153–6
 azeotropes, 148–51
 comparison of adhesives, 122
 cyanate esters, 129–31
 electrical properties, 124–5, 126
 end sealants, 265
 epoxy adhesives, 121–5
 film adhesives, 132–3, 134–6, 326
 main sealants, 264
 MCOT adhesives, 131, 132
 organic solvents, 148–51
 polyimides, 127–8
 polyurethanes, 128–9, 130
 sealants, 264, 265
 semi-aqueous cleaners, 153–6
 silicones, 125–7
 silver-glass adhesives, 133
 UV-curing adhesives, 131–2
pseudoplastic fluids, 42
Pull Test, Sebastian, 210
pumps, 192
purity: epoxy adhesives, 122–3
PWA (printed-wiring assembly), 10
PWBs (printed-wiring boards), 221
QA (quality assurance), 329–31
quad-flat packs (QFPs), 13–14
quadrupole mass spectrometry, 373
qualification criteria, 329
quality of adhesives, 320–1
quality assurance (QA), 329–31
radiation resistance, 246
radiation tests, 359
radiofrequency identification (RFID) units,
 280–2
radius of curvature (ROC), 296, 370–1
raining, 202
rear panel processing, 260–2, 263
receiving inspection, 329–30
rectangular dies: dispense pattern, 185,
 186
reflection: acoustic, 301
reflow soldering, 219
refractive index, 277–9, 355
relative humidity, 128
reliability, 289–344
 bathtub curve, 322–4, 325
 failure methodology, 290–2
 failure modes/mechanisms, 292–321
 flip-chip devices, 296
 hazardous materials restrictions, 336–42
 modeling, 321–8
 prediction, 321–8
 qualification criteria, 328–9
 quality assurance, 329–31
 specifications, 331–6
 standards, 336
residual stress, 66–7, 296–7
residual-gas analysis (RGA), 291, 317,
 318–19, 372–3
residue identification, 145
resistance, 51, 310, 311
resistivity, 51–4, 171
resistivity of solvent extracts (ROSE) test,
 171
Restriction of Hazardous Substances
 (RoHS), 336–42
rework, 209–12
RF frequencies, 167
RFID (radiofrequency identification),
 280–2
RGA *see* residual-gas analysis
rheology, 41–7
 capillary flow, 43–7
 fillers, 108–9

- rheology (*Continued*)
 Newtonian behavior, 42–3
 non-Newtonian behavior, 42–3
 screen printing, 178–80
 stencil printing, 178–80
 underfill adhesives, 232
- ROC *see* radius of curvature
- RoHS (Restriction of Hazardous Substances), 336–42
- room temperature vulcanizing (RTV), 89, 90
- ROSE (resistivity of solvent extracts) test, 171
- rotoviscometers, 351
- RTV silicones, 89, 90
- rubber-like materials, 113–14
- safety issues, 112, 114
- SAM *see* scanning-acoustic microscopy
- satellite dots, 195
- satellites, 246
- scanning acoustic microscopy (SAM), 281, 291, 300–1, 302, 369–70
- scanning calorimetry, 205–9, 361–2
- schedules *see* curing, schedules
- screen cleaning, 153–6
- screen printing, 173, 174–81
 adhesive material, 178–80
 adhesive properties, 179–80
 equipment, 180
 process, 180
 rheology properties, 178–80
- screen tests, 330–1
- sealants, 264, 265
- Sebastian Pull Test, 210
- security devices, 31, 32
- selective dispensing *see* automated selective dispensing
- semi-aqueous cleaners, 147–52, 153–6, 162–3, 165
- semiconductor devices: electrical contact loss, 310–12
- semiconductor die attachment, 134
- shape factors: underfill fillets, 46–7
- shear thickening, 42
- shear thinning, 42, 43
- shelf life:
 die-attach adhesives, 228–30
 solder replacement adhesives, 243–4
- substrate-attach adhesives, 228–30
- surface-mount adhesives, 222–3
- shielding: electromagnetic interference, 274–5, 276
- Shore Durometer hardness test, 292
- shrinkage reduction: fillers, 107–8
- shut-off distance: automated dispensing, 185–6
- Siemens Standard SN 59651, 331, 337–9
- silanes, 48, 49, 113
- silicon IC device: fracture, 303
- silicones:
 addition polymerization, 89–91
 catalysts, 89
 chemistry, 88–91
 condensation polymerization, 89, 90
 cross-linkers, 89
 linear structure, 89
 moisture-curing, 91
 polymer structure, 89
 properties, 125–7
 electrical properties, 126
 humidity resistance, 126
 mechanical properties, 126–7
 moisture-vapor transmission rates, 126
 physical properties, 126–7
 thermal properties, 125–6
 thermomechanical properties, 125–6
- RTV synthesis, 90
- step-growth polymerization, 90
- types, 89
- silver-filled adhesives, 7, 8, 53, 102–7
- silver migration, 316
- suppliers, 105–6
- thermal conductivity, 285
- silver-glass adhesives, 4, 50, 101, 133, 297
- silver-glass bonding, 26, 29
- silver-palladium fillers, 102, 104
- single-chip packaging, 12–19. *See also* chip-scale packages
- SIP *see* system-in-package
- SIPLACE component placement systems, 199–200
- SIR (surface-insulation resistance) test, 171–2
- slot design: stencils, 177, 179
- slump tests, 352
- smart cards, 31, 280–2

- Smart Sonic Series cleaning equipment, 163
SMAs *see* surface-mount adhesives
SMT *see* surface-mount technology
snap-cured adhesives, 5, 201
“snow cleaning”, 168
solder replacement adhesives, 11, 240–2, 243–4, 312–14
soldering, 26, 29, 219
solid adhesives, 5
solid carbon dioxide (CO_2) cleaning, 168
solid-state devices, 30
solid-state LEDs, 269
solvent resistance tests, 358–9
solvent-based adhesives, 5
solvents, 103
 aqueous cleaners, 147–52, 153–6
 centrifugal cleaning, 165
 cleaning ability, 152–9
 co-solvents, 147
 density, 158, 159
 emulsion cleaners, 147
 hydrochlorofluorocarbons, 146, 147
 Kauri-Butanol value, 148–51
 organic solvents, 146–7, 148–51
 selection, 146–59
 semi-aqueous cleaners, 147–52, 153–6
 solvency measurement, 152–9
 suppliers, 158, 159
 surface tension, 158, 159
 viscosity, 158, 159
 wetting index, 158, 159
space electronics, 246–7
specific conductance, 51–4, 102–7, 133
specific gravity tests, 352–3
specifications, 29–30, 331–6
 die-attach adhesives, 331, 332–3
 electronic components/systems, 245
 substrate-attach adhesives, 331, 332–3
 surface-mount adhesives, 331, 337–9
 underfill adhesives, 336, 340–1
spectrometry, 317, 372–3
spectroscopy, 204–5, 206, 207, 292, 320–1, 322, 374
Speedline Technologies cleaning equipment, 165
spray cleaning, 161–4
spray wands, 160
spread tests, 352
square dies: dispense pattern, 185
squeegee stroke, plastic stencils, 177, 178, 180
stabilizers, 116
stackable interconnect vias, 259
stacking of multichips, 19–24, 254
stamp transfer, 182–3
standards, 249, 324–8, 331, 336, 337–9, 350
Staychip underfill adhesives, 232
stencil printing, 173, 174–81
 adhesives, 178–80, 181
 critical variables, 176
 equipment, 180
 process, 180
 rheology properties, 178–80
 suppliers of adhesives, 181
 variables, 176
stencils:
 chemical etching, 176
 cleaning, 153–6
 design/fabrication, 176–8, 179
 dots and lines, 177
 electroformed stencils, 176
 laser-cut stencils, 176
 plastic stencils, 176–7, 178
 thickness, 177–8
step curing, 71
sterilization of medical devices, 249–50
stoichiometric level, 87
strain energy release rate method, 304–5
stress dissipation, 8, 60–71
 glass transition temperature, 62–6
 residual stress, 66–7
 thermal expansion/stress, 61–2, 63–5
stress-intensity method, 304, 305
stresses:
 curing conditions, 71
 delamination, 295–302
 dissipation, 8, 60–71
 gelation, 71
 part stress analysis, 327
 residual stress, 66–7, 296–7
stringing, 194–5
substrate materials, 271, 273
substrate-attach adhesives, 9
 applications, 224, 225, 226, 227
 coefficient of thermal expansion, 228–30
 cure schedule, 228–30
 defects, 354
 film adhesives, 135–6

substrate-attach adhesives (*Continued*)

- ionic impurities, 228–30
- outgassing, 247
- pot life, 228–30
- properties, 228–30
- rework, 211–12
- shelf life, 228–30
- specifications, 331, 332–3
- strength testing, 369
- suppliers, 228–30
- testing, 332–3
- thermal conductivity, 228–30
- viscosity, 228–30
- volume resistivity, 228–30
- substrates, 20, 21, 22
- suppliers:
 - anisotropic adhesives, 268
 - aqueous cleaners, 153–6, 162–3
 - automated dispensing systems, 190–1
 - azeotropes, 148–51
 - capillary-flow underfill adhesives, 236–7
 - centrifugal cleaning equipment, 165
 - chip-scale packages, 252–3
 - component placement systems, 199–200
 - die-attach adhesives, 228–30, 247
 - epoxy resins, 81
 - no-flow underfills, 236–7
 - organic solvents, 148–51
 - pin transfer adhesives, 183
 - plasma cleaning systems, 169–70
 - Polyurethanes, 130
 - preform adhesives, 238
 - pressure-sensitive adhesives, 266
 - semi-aqueous cleaners, 153–6, 162–3
 - silver fillers, 105–6
 - solder replacement adhesives, 243–4
 - solvents, 158, 159
 - stencil printing adhesives, 181
 - substrate-attach adhesives, 228–30, 247
 - surface-mount adhesives, 222–3
 - ultrasonic cleaners, 161
 - underfill adhesives, 234–5
 - UV-curing adhesives, 277–9
 - vapor degreasers, 161
- surface area: viscosity, 109
- surface contamination, 294–5
- surface energy tests, 353
- surface tension, 158, 159, 353
- surface treatments, 172–3

surface-insulation resistance (SIR) test, 171–2

- surface-mount adhesives (SMAs), 173–4, 178, 218
- automated selective dispensing, 186–92
- characteristics, 220–1
- coefficient of thermal expansion, 221, 222–3
- cure schedule, 222–3
- modulus of elasticity, 221
- pin transfer, 182
- pot life, 222–3
- shelf life, 222–3
- slump tests, 352
- specifications, 331, 337–9
- spread tests, 352
- suppliers, 222–3
- thermal conductivity, 222–3
- thixotropic hysteresis loops, 187
- thixotropic index, 222–3
- viscosity, 194, 222–3
- volume resistivity, 222–3, 224
- yield value, 221, 222–3
- surface-mount technology (SMT), 10, 19, 218–24
 - in-line modular equipment, 220
 - printed-circuit boards, 218–19
 - process steps, 220
 - reflow soldering, 219
 - wave soldering, 219
- surfactants, 40
- symbols, 380–4
- synthesis *see* chemistry
- syringe dispensing *see* automated selective dispensing
- system-in-package (SIP), 260, 261, 262
- TAB (tape-automated bonding), 7, 12
- tailing, 195
- tape adhesives, 3
- tape attachment, 197
- tape-automated bonding (TAB), 7, 12
- temperature:
 - automated dispensing, 187–8
 - capacitance, 129
 - cure time, 208, 209
 - stress generation, 297–8, 299
 - viscosity, 42
 - volume resistivity, 54

- tensile elastic modulus *see* modulus of elasticity
testing, 345–77
acceleration test, 291, 329
acceptance tests, 329–30
chemical analysis, 371–5
classification, 347–9
cleanliness, 168–72
collected volatile condensable materials test, 246
die-attach adhesives, 332–3
documents, 350
durometer test, 292
dye penetrant test, 291
electrical tests, 355–8
environmental tests, 358–60
government/industry documents, 350
hardness tests, 292, 366
mechanical tests, 365–71
nondestructive tests, 330–1
outgassing, 246
particle impact noise detection, 291, 320
physical tests, 346–55
screen tests, 330–1
Shore Durometer hardness test, 292
smart cards, 281, 282
standards, 350
substrate-attach adhesives, 332–3
summary of tests, 347–9
thermal tests, 360–5
thermomechanical tests, 365–71
undefill materials, 340–1
- TGA *see* thermogravimetric analysis
theory of adhesives, 35–74
thermal conductance, 55–60
thermal conductivity, 55–60, 308, 362–4
component-attach materials, 272
die-attach adhesives, 228–30
epoxy adhesives, 103, 123
fillers, 102–7, 285
silver-filled adhesives, 285
silver-glass adhesives, 133
solder replacement adhesives, 243–4
substrate materials, 271, 273
substrate-attach adhesives, 228–30
surface-mount adhesives, 222–3
underfill adhesives, 234–5
units/equivalents, 379
thermal curing, 201–2
- thermal cycling, 324, 326
thermal dissipation, 54–60
thermal expansion *see* coefficient of thermal expansion
thermal impedance, 307–9
bond line thickness, 308–9
outgassing, 309
thermal conductivity, 308
voids, 309
- thermal resistance, 272, 284–5
- thermal stability:
epoxy adhesives, 123, 124
fillers, 107
silver-glass adhesives, 133
test methods, 361
- thermal tests, 360–5
differential scanning calorimetry, 361–2
flammability testing, 365, 366
thermal conductivity, 362–4
thermogravimetric analysis, 364–5
- thermal weight loss, 127
- thermal-phase cleaning, 147–52
- thermally conductive adhesives, 8, 132, 256–7
- thermode method: die removal, 210–11
- thermogravimetric analysis (TGA), 123, 127, 364–5
- thermomechanical analysis (TMA), 66, 367
- thermomechanical properties, 123, 125–6
- thermomechanical tests, 365–71
acoustic microscopy, 369–70
bond strength, 367–9
coefficient of thermal expansion, 367
curvature radius, 370–1
flexural modulus, 366–7
glass-transition temperature, 367
hardness, 366
modulus and elongation, 366–7
radius of curvature, 370–1
tensile modulus, 367
- thermoplastic adhesives:
applications, 27
components, 211
preforms, 197
properties, 3–4
relative strength, 212
removal methods, 211–12
residual-gas analysis, 317, 319

- thermosetting adhesives:
 preforms, 197
 properties, 4
 relative strength, 212
 requirements, 276
- thick-film hybrid microcircuits, 21
- thin-film hybrid microcircuits, 21
- thixotropic agents, 112–13
- thixotropic fluids, 42
- thixotropic hysteresis loops, 187
- thixotropic index, 42, 222–3
- thixotropy: test methods, 351–2
- ThreeBond sealants, 264, 268
- through-silicon vias (TSV), 259–60
- time-pressure pump method, 192
- time-temperature-transformation (TTT)
 diagram, 68
- tin-lead soldering, 11, 26, 29
- titanium dioxide particles, 112
- TMA (thermomechanical analysis), 367
- TML (total mass loss), 246, 373–4
- TO (transistor outline) cans, 13
- torque strength, 37
- total light transmittance, 355
- total mass loss (TML), 246, 373–4
- toxicity, 112, 114, 249
- transistor outline (TO) cans, 13
- TSV (through-silicon vias), 259–60
- TTT (time-temperature-transformation), 68
- two-pad devices: stencil patterns, 179
- two-part adhesives, 3
- types of adhesives, 2–11
- “U” dispense pattern, 193, 194
- ultrasonic cleaning, 161, 164
- ultraviolet *see* UV...
- underfill adhesives, 11, 43–7
 alternate approaches, 238–40
 applications, 224–40
 automated dispensing, 192–4
 capillary-flow, 224–5, 231
 coefficient of thermal expansion, 234–5
 cure schedule, 234–5
 fillet shape factors, 46–7
 flow properties, 232
 ionic impurities, 234–5
 moisture absorption, 234–5, 301
 no-flow underfills, 226–38
 polymer-film interconnect, 240
- pre-applied underfills, 240
- preforms, 238
- properties, 232, 234–5
- specifications, 336, 340–1
- stresses, 296
- suppliers, 234–5
- thermal conductivity, 234–5
- underfill time/distance function, 46
- viscosity, 234–5
- volume control, 46
- volume resistivity, 234–5
- wafer-level underfill, 238–40
- wettability, 45
- underfill flip-chip devices, 212
- underfill preform adhesives *see* film adhesives
- units/equivalents, 379
- useful life period: bathtub curve, 323, 325
- UV-curing adhesives, 5–6, 202–3, 267, 276–9
 applications, 277–9
 cure conditions, 277–9
 properties, 131–2
 refractive index, 277–9
 suppliers, 277–9
 tensile strength, 277–9
 viscosity, 277–9
 water absorption, 277–9
- UV-indicators, 117
- UV-stabilizers, 116
- vacuum baking, 40, 41
- valves, 196
- vapor degreasing, 159–61
- variable-frequency microwave (VFM)
 curing, 6, 203
- vertical-stack packaging, 251–60
 benefits, 257
 chip stacking, 251
 design types, 254
 multichip stacking, 254
 package stacking, 251
 through-silicon vias, 259–60
 wafer stacking, 254–8
- Vertrel azeotropes, 149
- VFM (variable-frequency microwave), 6, 203
- viscometers, 45, 351

- viscosity:
automated dispensing, 194
Cab-O-Sil filler, 109
component placement time, 184
conversion factors, 380
definition, 41
die-attach adhesives, 228–30
dispensing, 184
epoxy adhesives, 41, 42, 81
increase, 39
lowering, 44–5
measurement, 45
Newtonian behavior, 42, 43
non-Newtonian behavior, 42, 43
polyurethanes, 130
pot life, 194
screen printing, 180
solder replacement adhesives, 243–4
solvents, 158, 159
stencil printing, 180
substrate-attach adhesives, 228–30
surface treatments, 109
surface-mount adhesives, 194,
 222–3
temperature function, 42
test methods, 346–51
underfill adhesives, 44–7, 234–5
underfill time, 46
UV-curing adhesives, 277–9
visible light curing, 202–3
visual inspection, 353–5
vitreous attachment, 26, 29, 50–1
voids, 202, 300, 309
volatiles: test methods, 246, 371
volume fractions, 54, 55
volume resistivity, 51, 52
 cure conditions, 53
 die-attach adhesives, 228–30
 solder replacement adhesives, 243–4
substrate-attach adhesives, 228–30
surface-mount adhesives, 222–3,
 224
temperature, 54
- test methods, 356
underfill adhesives, 234–5
- wafer scale packaging (WSP), 254–8,
 259, 260
wafer stacking, 254–8
wafer-level CSP (WLCSP), 18, 253
wafer-level packaging (WLP), 31
wafer-level underfill (WLU), 238–40
water vapor regained (WVR), 374
water-drop spreading test, 168. *See also*
 aqueous cleaners; moisture
wave soldering, 219
wearout period: bathtub curve, 323, 325
Weibull analysis, 323–4
weight loss, 127, 371
wettability:
 contact angles, 38, 39
 inadequacy, 294–5
 theory, 37–41
wetting index (WI), 158, 159
White LXM3-PWx1 LED light, 271
WI (wetting index), 158, 159
wire bonding, 12
wireless devices, 275
wiring harnesses, 153–6
WLCSP (wafer-level CSP), 18, 253
WLP (wafer-level packaging), 31
WLU (wafer-level underfill), 238–40
WSP (wafer scale packaging), 254–8,
 259, 260
WVR (water vapor regained), 374
- XyFlexPRO automated dispensing systems,
 190–1
- yield value, 180, 221, 222–3, 352
Young-Dupree equation, 38
Young's equation, 37
Young's modulus *see* modulus of elasticity
- z-directional adhesives, 7
Zestron organic solvents, 149–50